

Infineon Roadshow

April 2007

Peter J. Fischl

Executive Vice President and CFO

Ruediger Andreas Guenther

CFO Designate



Never stop thinking

Disclaimer

This presentation was prepared as of March 23, 2007 and is current only as of that date.

This presentation includes forward-looking statements about the future of Infineon's business and the industry in which it operates. These include statements relating to future developments in the world semiconductor market, including the market for memory products, Infineon's future growth, the benefits of research and development alliances and activities, Infineon's planned levels of future investment in the expansion and modernization of its production capacity, the introduction of new technology at its facilities, the continuing transitioning of its production processes to smaller structure sizes, cost savings related to such transitioning and other initiatives, Infineon's successful development of technology based on industry standards, Infineon's ability to offer commercially viable products based on its technology, Infineon's ability to achieve its cost savings and growth targets, and the impact of the carve-out of Qimonda, the group's memory products business, its initial public offering, and any further sales of Qimonda shares or other corporate financing measures in that regard.

These forward-looking statements are subject to a number of uncertainties, including trends in demand and prices for semiconductors generally and for Infineon's products in particular, the success of Infineon's development efforts, both alone and with partners, the success of Infineon's efforts to introduce new production processes, the actions of competitors, the availability of funds for planned expansion efforts, and the outcome of antitrust investigations and litigation matters, as well as the other factors mentioned in this presentation and those described in the "Risk Factors" section of the annual report of Infineon on Form 20-F filed with the U.S. Securities and Exchange Commission on November 30, 2006 or contained in the company's quarterly reports. As a result, Infineon's actual results could differ materially from those contained in these forward-looking statements. You are cautioned not to place undue reliance on these forward-looking statements.

Infineon does not undertake any obligation to publicly update or revise any forward-looking statements because of new information, future events or otherwise.

Table of Contents

■ Group Financials and Targets

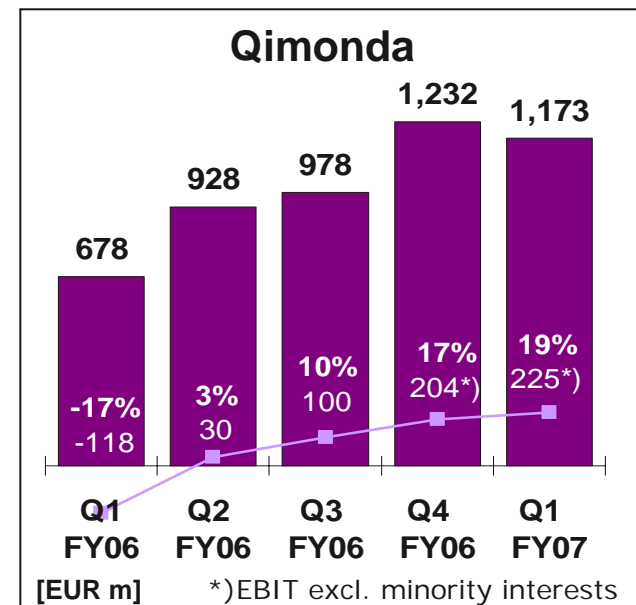
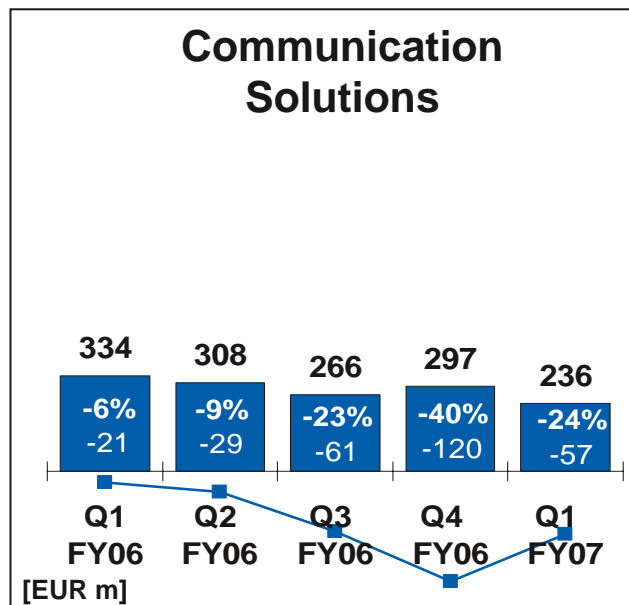
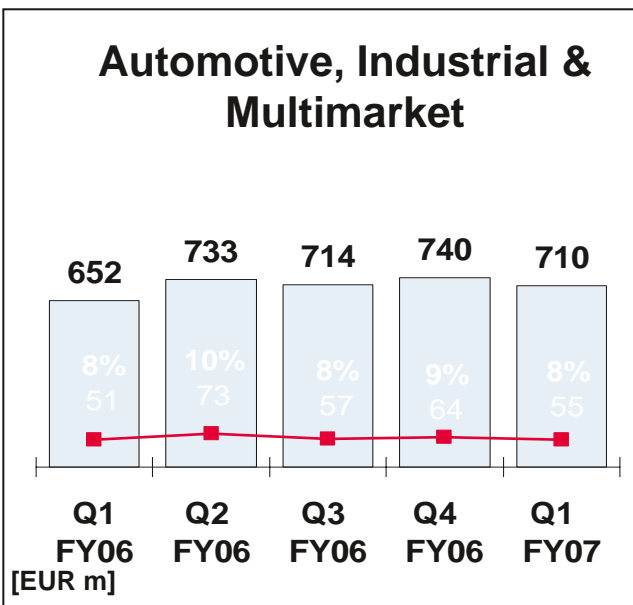
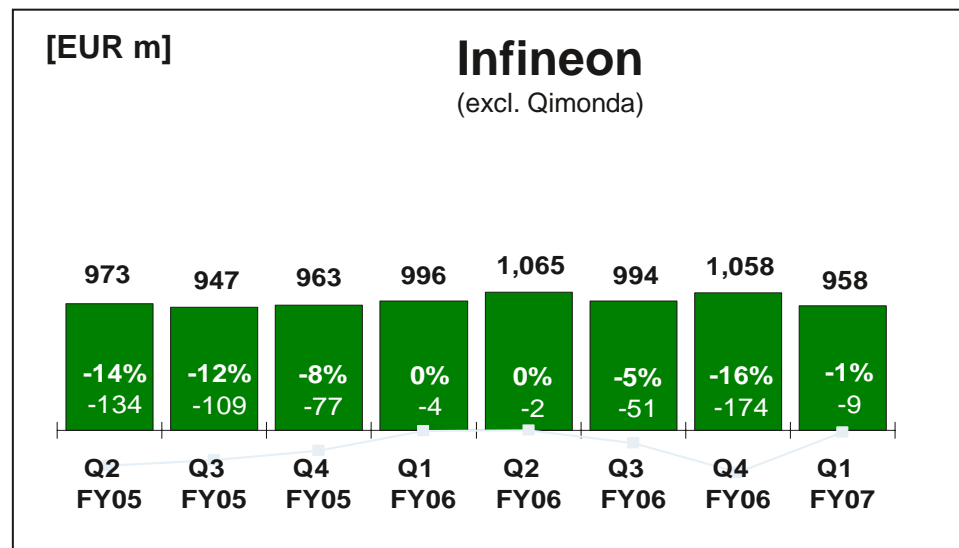
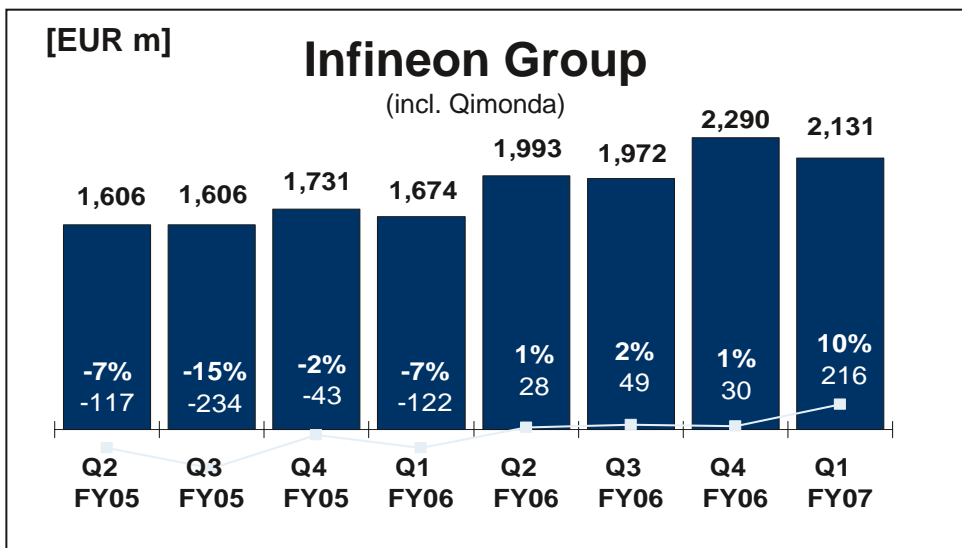
■ COM Products and Structure

- Wireless
- Wireline

■ AIM Products and Structure

- Automotive
- Industrial & Multimarkets
- Security & ASICs

First Quarter FY 2007 Results: Rev. of EUR 2.13 bn; EBIT of EUR 216 m



Second Quarter FY 2007 Outlook

IFX Logic

Revenues and EBIT excluding Qimonda and before charges are expected to remain at least flat

COM

- Revenues and EBIT flat q-o-q
- Customer ramp-ups mitigate typical seasonal decline in the wireless business; wireline business to be about flat

AIM

- Revenues to increase slightly q-o-q; EBIT margin to improve
- Auto to grow on ramp-ups and seasonality despite continued U.S. auto weakness. Industrial & Multimarket and Security & ASIC to remain broadly flat

C & E

- EBIT loss before charges basically unchanged q-o-q
- Charges: significantly less than the EUR 30 m expected originally mainly for baseband restructuring

Group Results and FY 2007, FY 2008 Outlook (excluding Qimonda)

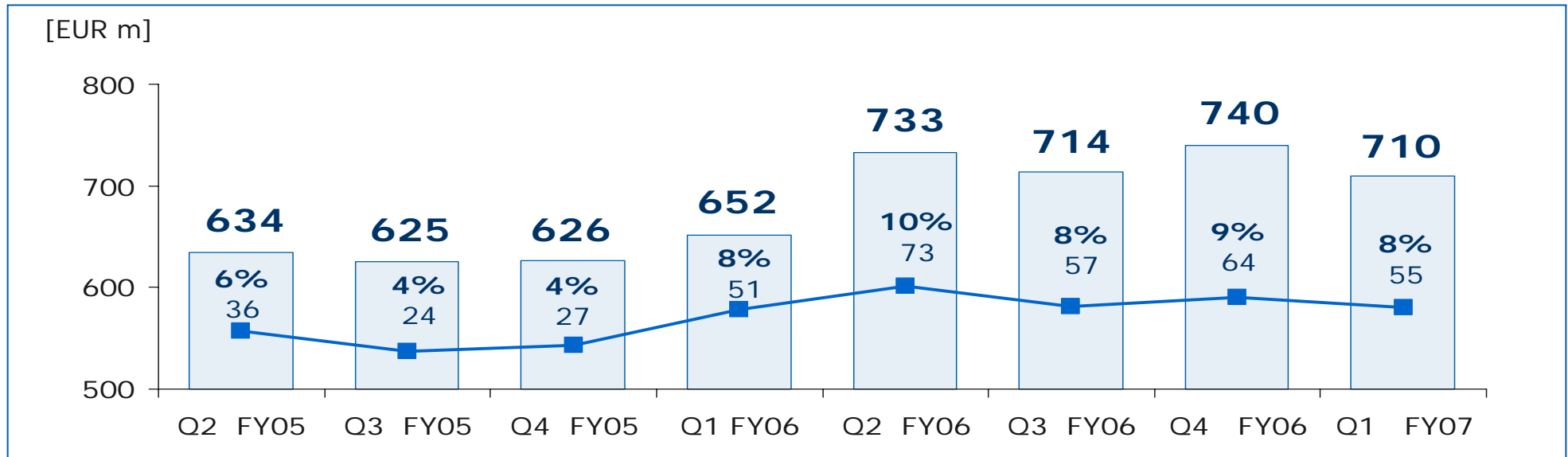


	FY 2005	FY 2006 ^{*)}	FY 2007	FY 2008
in EUR m				
Sales	3,933	4,114		
Gross Profit (Gross margin)	1,187 (30%)	1,308 (32%)		
R&D	902	816	760-800	
SG&A	449	536	500-540	
EBIT (EBIT margin)	-305 (-8%)	-217 (-5%)		

Infineon defines EBIT as Earnings (loss) Before Interest and Taxes.

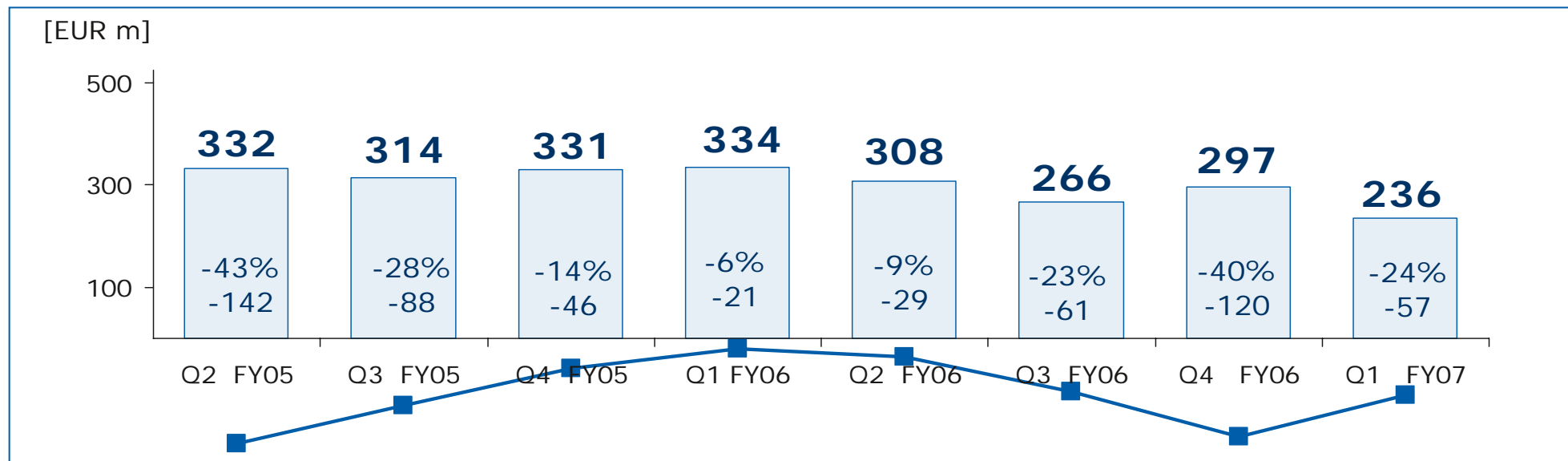
*) FY2006: Includes net charges of € 199 million relating primarily to various impairments and restructuring measures as well as expenses incurred in connection with the insolvency of BenQ Mobile Germany and the IPO of Qimonda.

Automotive, Industrial & Multimarket Results and Outlook



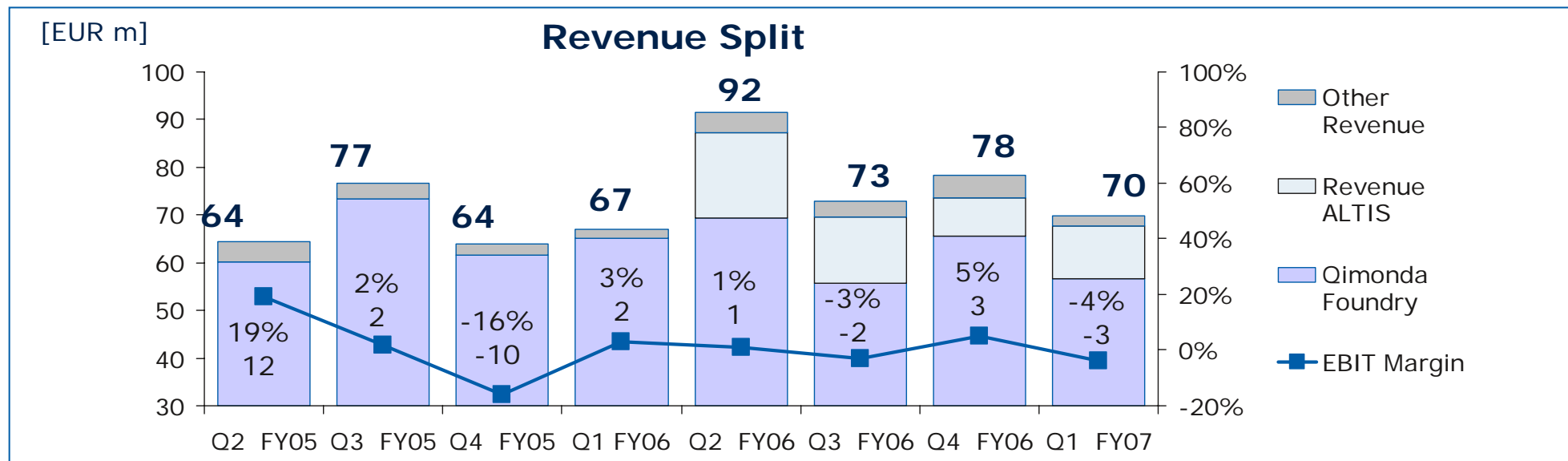
- FY 2006: more than € 70m expenses from Perlach/Kulim fabs; losses in Chipcard.
- FY 2007: expect sales growth y-o-y; EBIT likely to rise y-o-y; close to 10% EBIT margin for Q4 FY 2007.
- FY 2007: Expenses for Perlach closure and Kulim ramp similar to FY 2006 levels
→ Perlach closed, Kulim start-up expense to run out Q4 FY 2007.
- Beyond FY 2007: continued sales growth, >10% EBIT margin.

Communication Solutions Results and Outlook



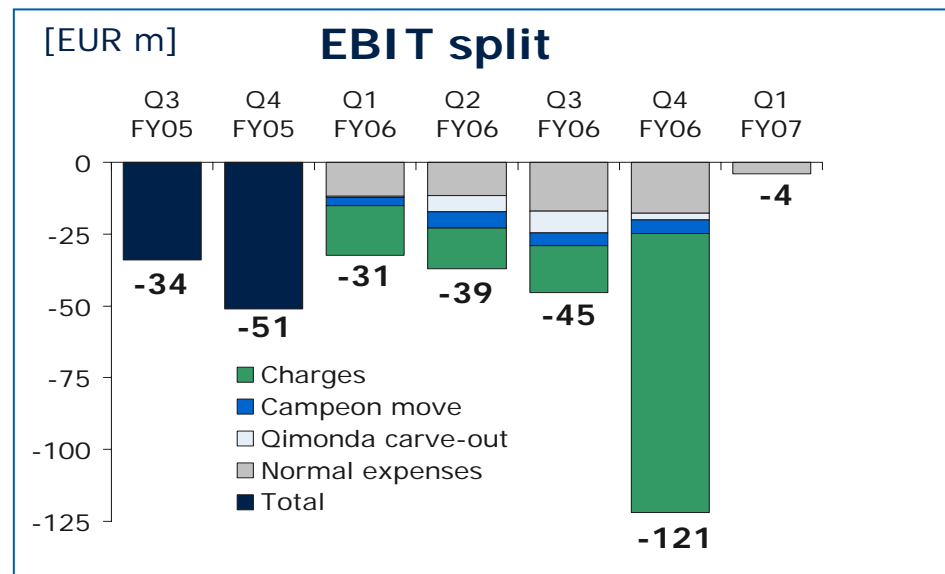
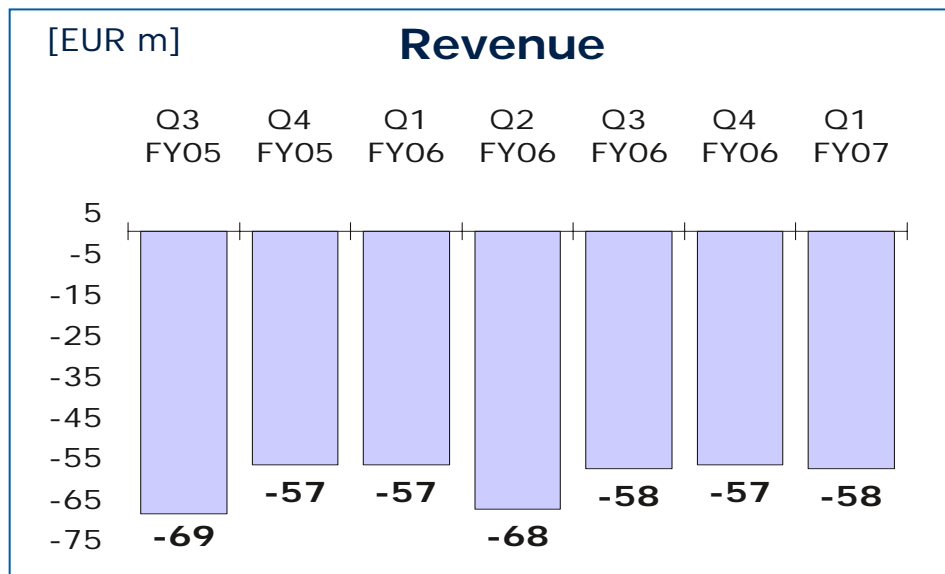
- FY 2006: € 92m in charges included in results, mainly relating to BenQ insolvency; clean EBIT € -139m.
- FY 2007: expect sales decline y-o-y; expect annualized c. € 40 m cost reduction from Jun Q onwards; EBIT before special effects to remain broadly flat y-o-y.
- Beyond FY 2007: Wireless business to break-even in Dec Q 2007; expect strong sales growth vs FY 2007 and positive EBIT.

Other Operating Segments Results and Outlook



- FY 2007: share of loading of ALTIS fab 100% since 1-Jan-07; agreement with Qimonda over Dresden 200mm fab extended to 30-Sep-2009; sales to trend lower.
- FY 2007: EBIT around break-even.
- Beyond FY 2007: Sales to decline gradually as revenues with Qimonda move lower; EBIT around break-even.

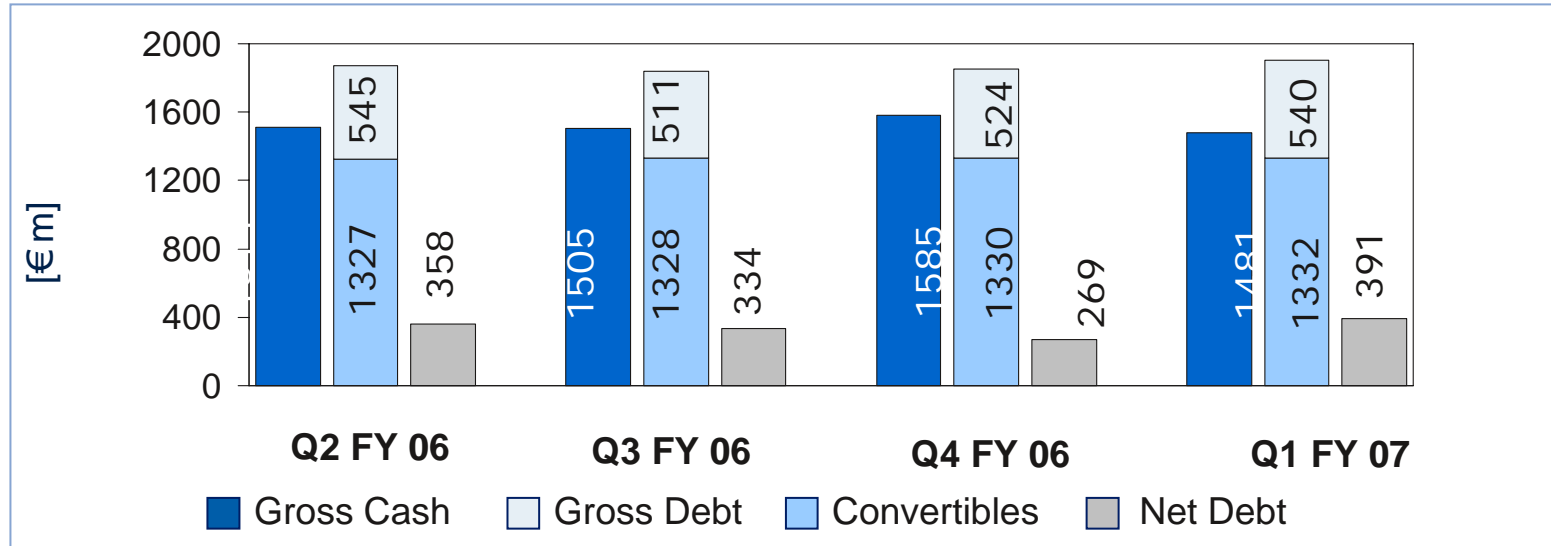
Corporate & Eliminations Results and Outlook



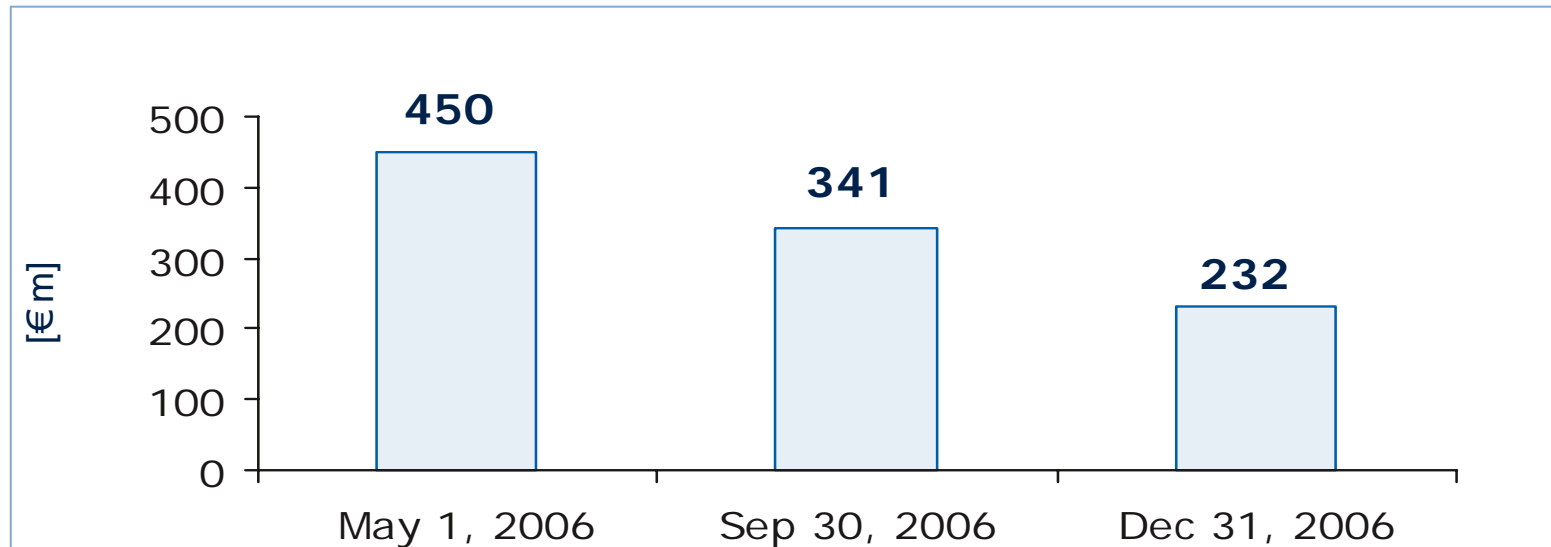
- FY 2006: Sales are negative as intra-group wafer deliveries to Qimonda are being eliminated; EBIT contains net charges of EUR 105 m relating mainly to Qimonda IPO (EUR 65 m) and to restructuring measures (EUR 25 m). Ongoing expenses in C&E: e.g. stock options, idle capacity cost, elimination of intra-group profits on wafers sold to Qimonda.
- FY 2007: negative sales to persist due to inter-company elimination; amount driven by sales to Qimonda in OOS. EBIT before charges to improve significantly from FY 2006 level to c. EUR -60 m. Expect charges around EUR 30 m for baseband and ALTIS combined.
- Beyond FY 2007: Expect to contain EBIT loss excluding charges at approximately FY 2007 levels.

Gross Cash, Gross Debt and Net Debt

Financial structure of the Logic business for the past quarters

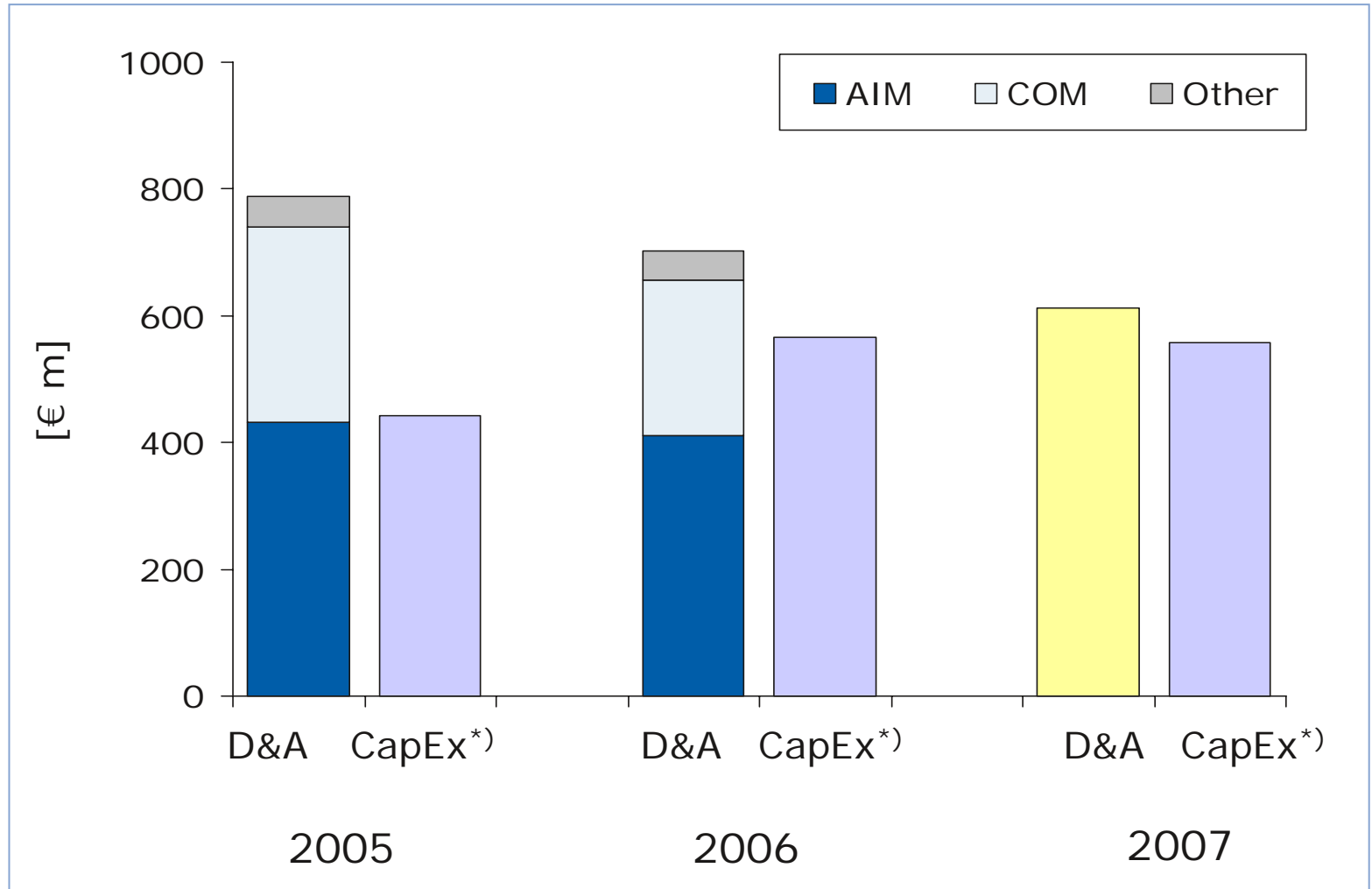


Development of the inter-company loan to Qimonda



Target CapEx/Sales 10-12% beyond FY 2007

Capital intensity
Logic business



*) w/o intangibles

Infineon Businesses

Communication Solutions

Mobile Phone Platforms

Feature Phones

Entry Phones

Mobile Software

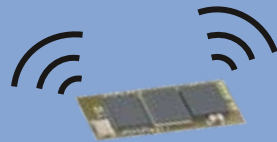


RF Solutions

RF Engine

Tuner Systems

Connectivity



Broadband

Access



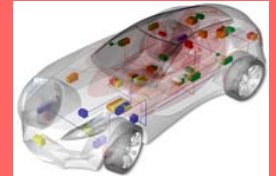
Automotive, Industrial & Multimarket

Automotive

Microcontroller

Automotive Power

Sense & Control



Industrial & Multimarket

Power Management & Drives

Discrete Semiconductors



Security & ASICs

ASIC Design & Security

Chip Card & Security ICs



Table of Contents

■ Group Financials and Targets

■ COM Products and Structure

- Wireless
- Wireline

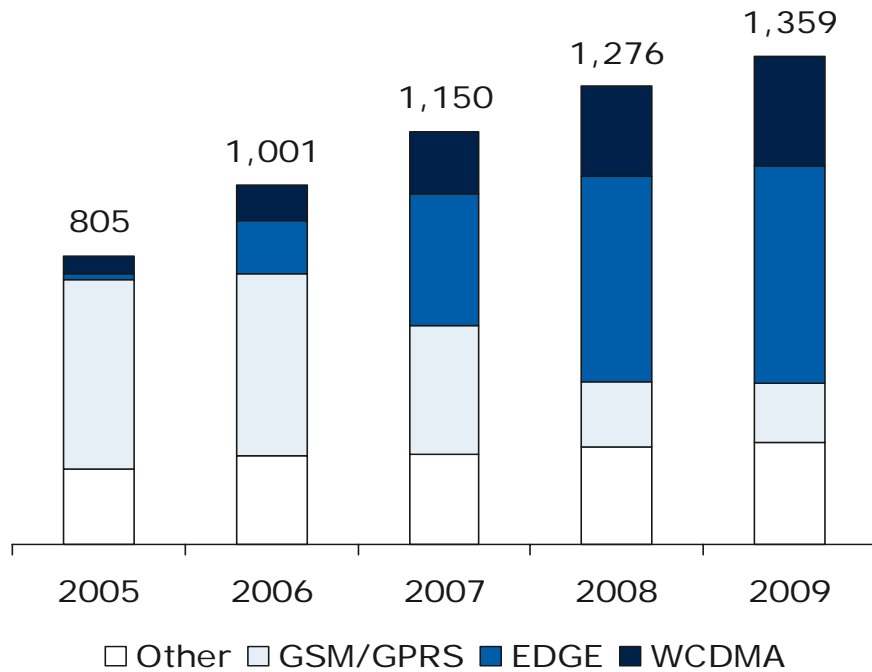
■ AIM Products and Structure

- Automotive
- Industrial & Multimarkets
- Security & ASICs

Major COM Growth Opportunities

Mobile Phones

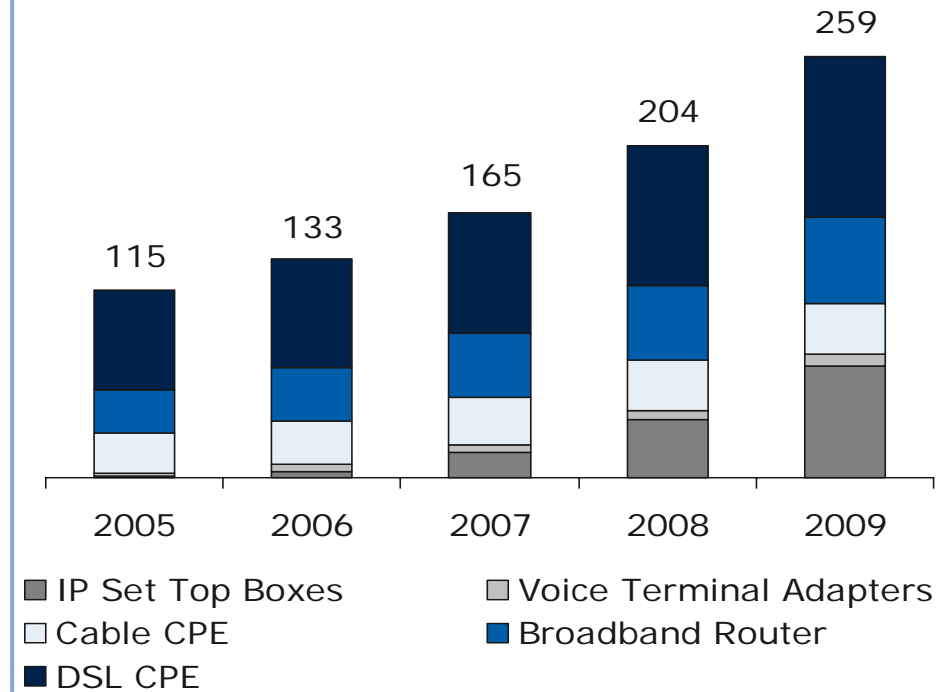
[units m]



Source: ABI Research, Mobile Device Market Data, Q4 2006

Broadband CPE

[units m]



Source: Infonetics, Broadband CPE, Q3 2006

Infineon Engineers Develop World-Class Products

Single-chip
EDGE mobile phone
solution

"S-GOLDradio"



Single-chip
GSM mobile phone
solution

"E-GOLDvoice"



Single-chip
7.2 Mb/s HSDPA
baseband

"S-GOLD3H"



World's first
3G/EDGE DigRF
CMOS transceiver

"SMARTI UE"



World's smallest EDGE
CMOS transceiver

"SMARTi PM+"



Single-chip
Mobile TV
front-end

"OmniVia"



World's smallest
GPS single-chip receiver

"Hammerhead II"



World's first stan-
dard compliant
VDSL2 solution

"VINAX"



World's first single-
chip ADSL2+
broadband IAD

"Danube"



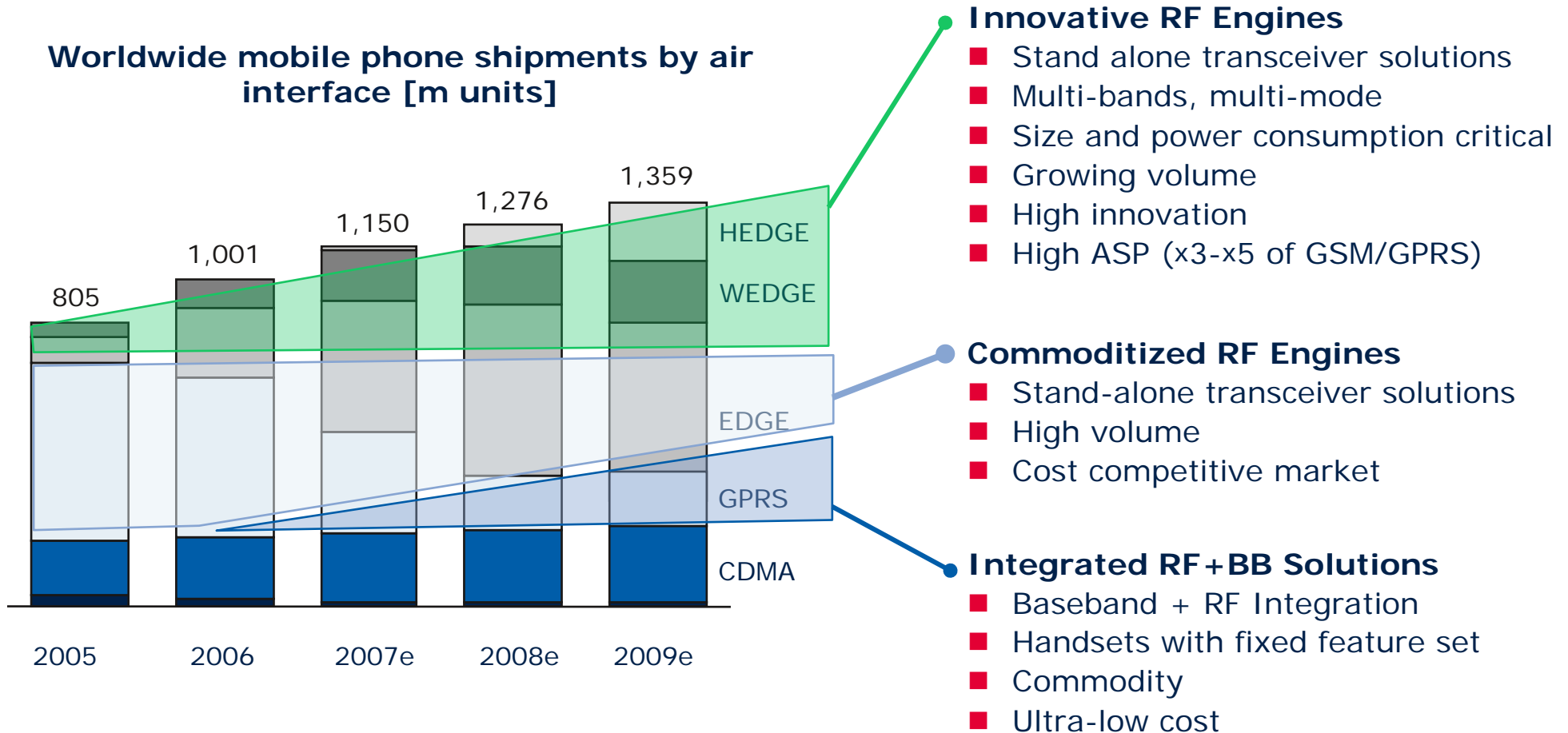
World's first
5+2G switch

"Tantos"



Market Segmentation

Worldwide mobile phone shipments by air interface [m units]




Source: ABI Research, 2006; IFX

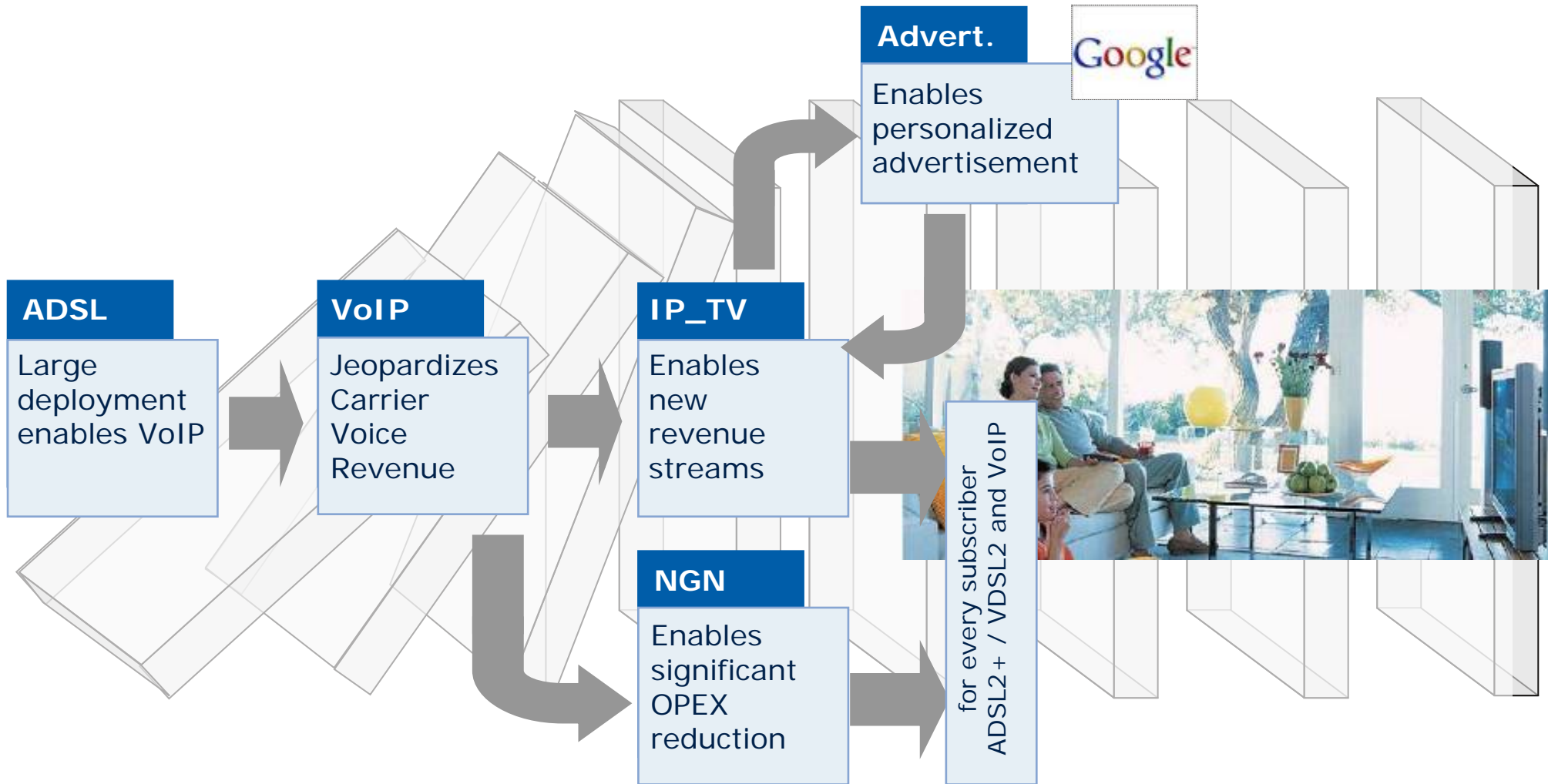
Complete Mobile Phone Platform Solutions for Major Growth Markets



Target markets	2G / 2.5G GSM / GPRS		2.75G EDGE		3G UMTS	3.5G HSDPA
Platform	ULC1	ULC2	MP-E	MP-Elite	MP-EU	MP-EH
Baseband	✓ <i>E-GOLDradio</i>	✓ <i>E-GOLDvoice</i>	✓	✓ <i>S-GOLDradio</i>	✓	✓
RF CMOS transceiver	✓ <i>E-GOLDradio</i>	✓ <i>E-GOLDvoice</i>	✓	✓ <i>S-GOLDradio</i>	✓	✓
Power management	✓	✓ <i>E-GOLDvoice</i>	✓	✓ <i>S-GOLDradio</i>	✓	✓
Protocol stack	✓	✓	✓	✓	✓	✓
Ramp-up	✓	✓	✓	2H CY07	✓	CY 2007+

 Integrated in one chip

The "Domino Effect" Market Trends



Network Replacement Market Trends

NGN Basis Structure

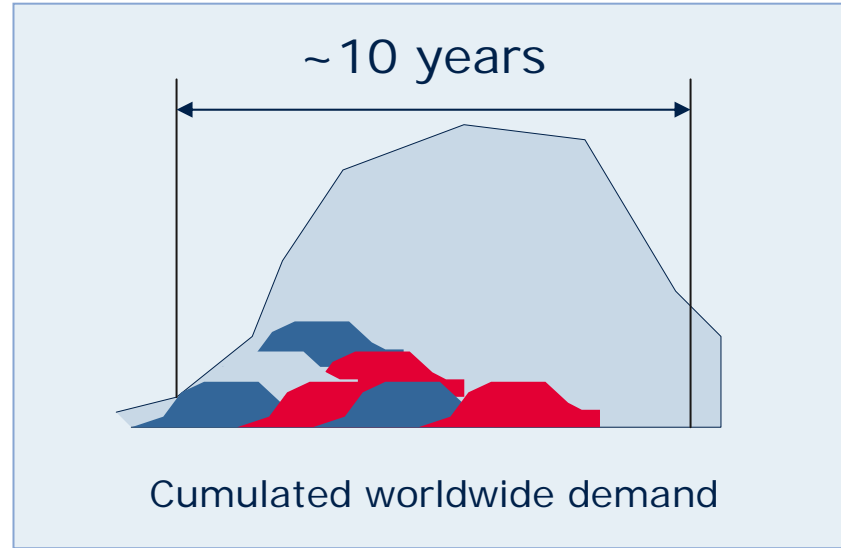
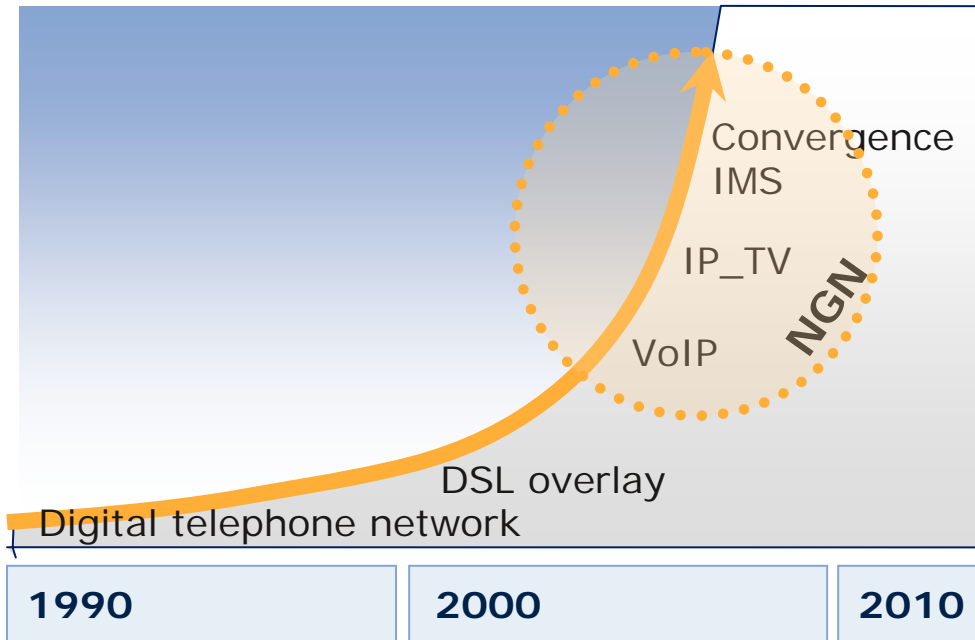
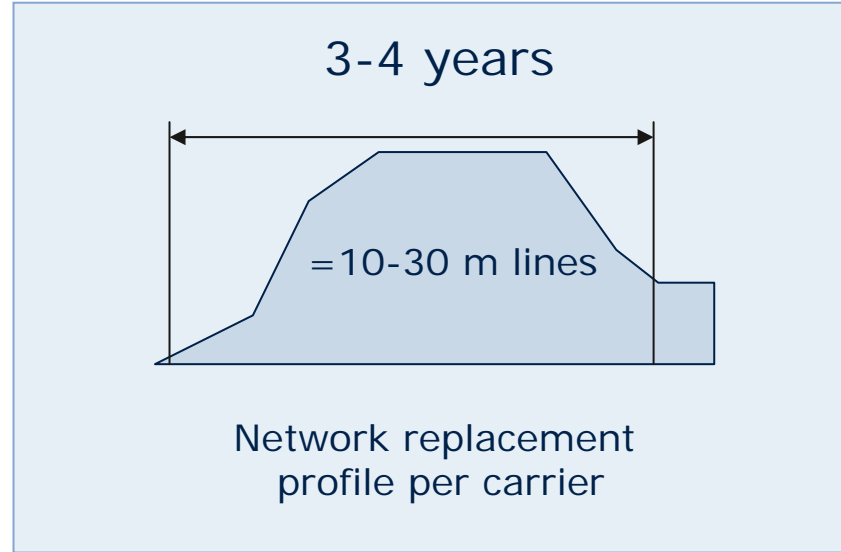
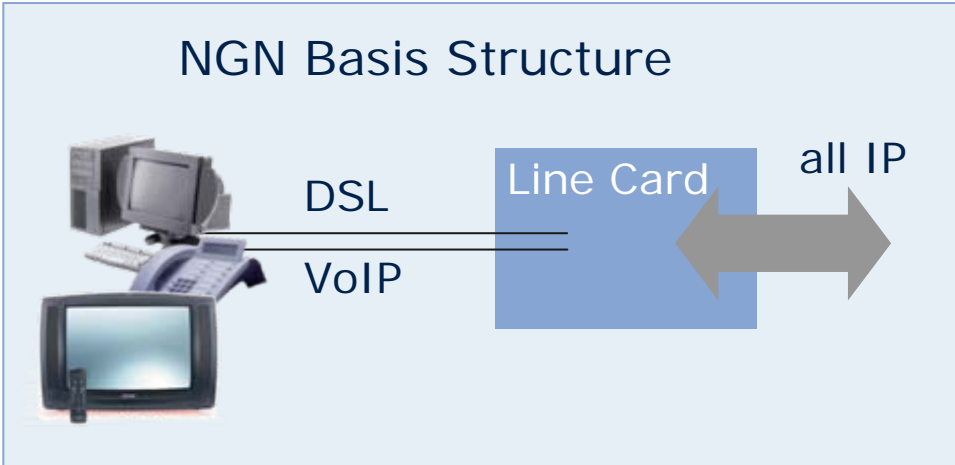


Table of Contents

■ Group Financials and Targets

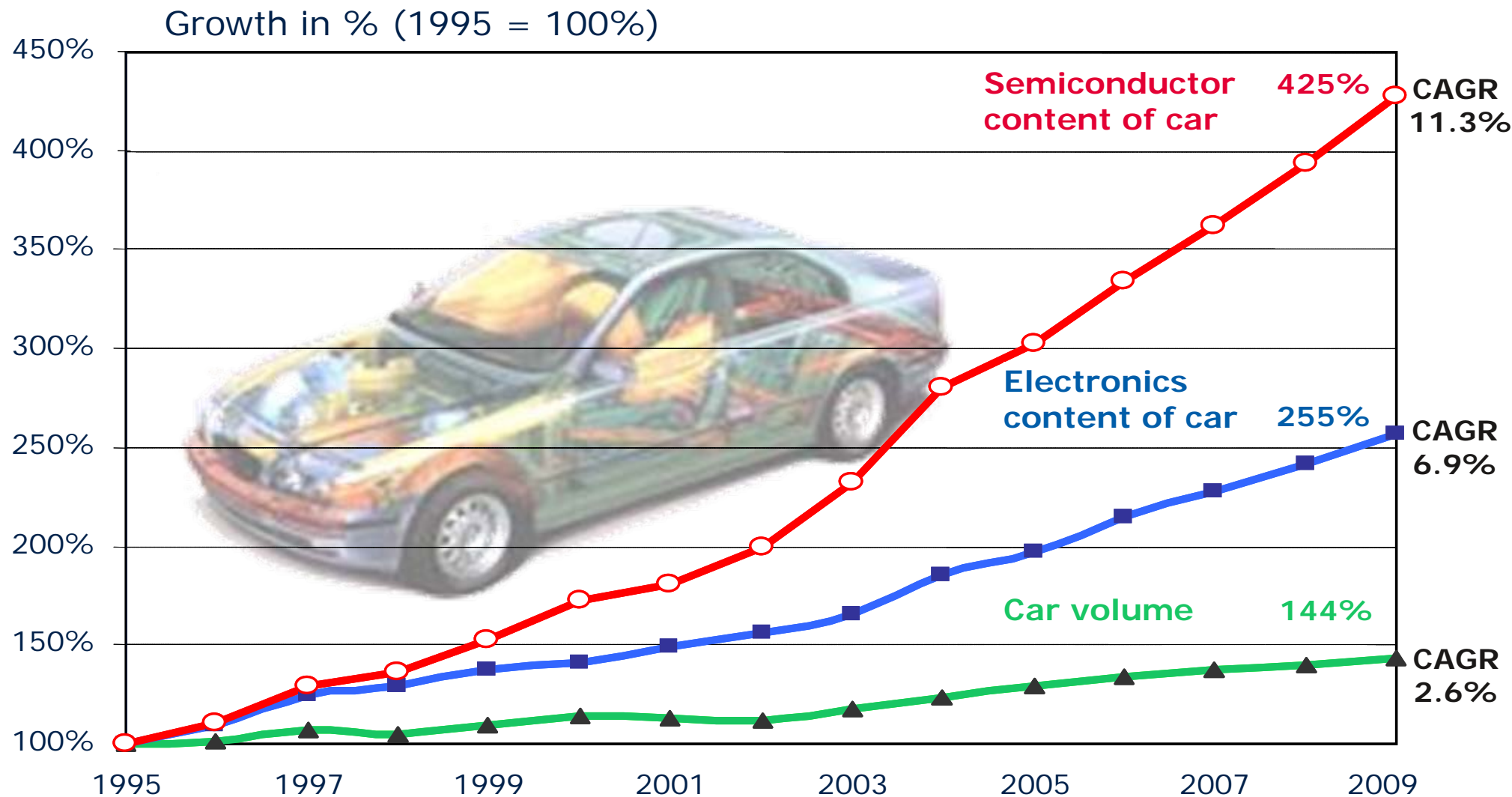
■ COM Products and Structure

- Wireless
- Wireline

■ AIM Products and Structure

- Automotive
- Industrial & Multimarkets
- Security & ASICs

Automotive Microelectronics Trends – More Than 50% of \$-value of Electronics is Semiconductors

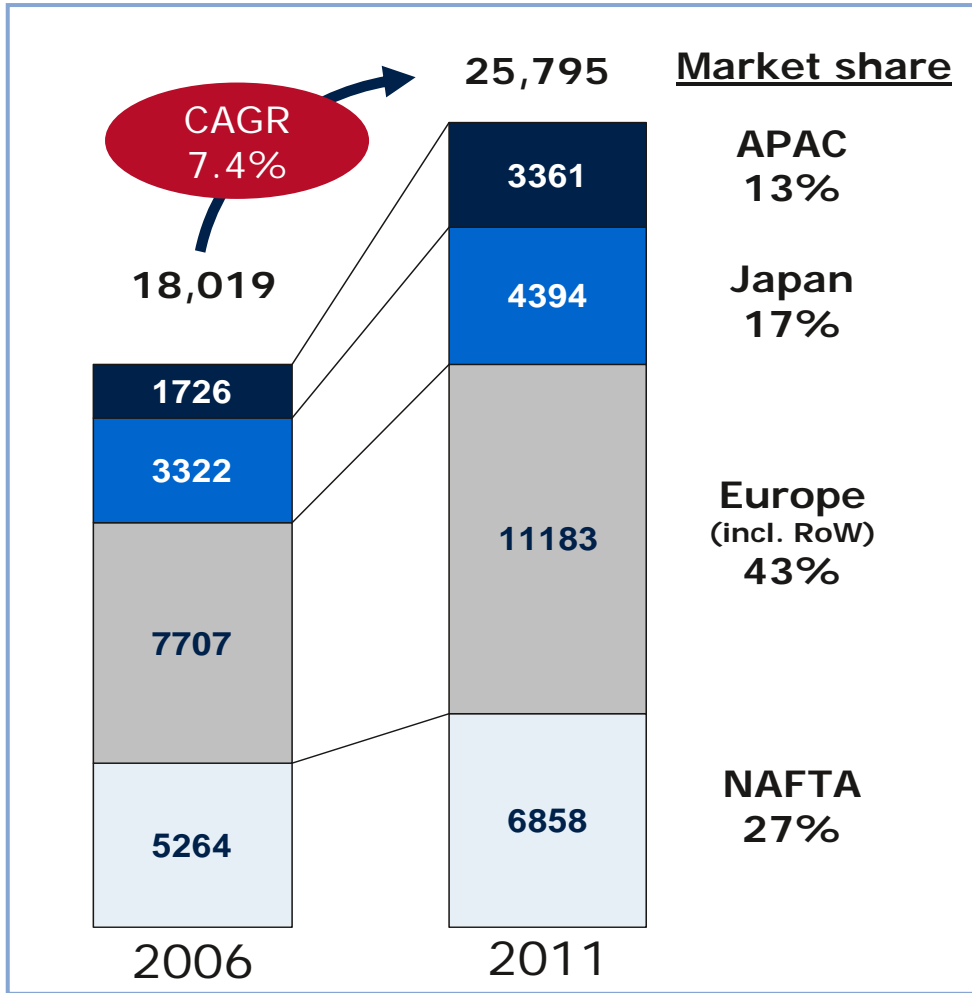


Source: ZVEI

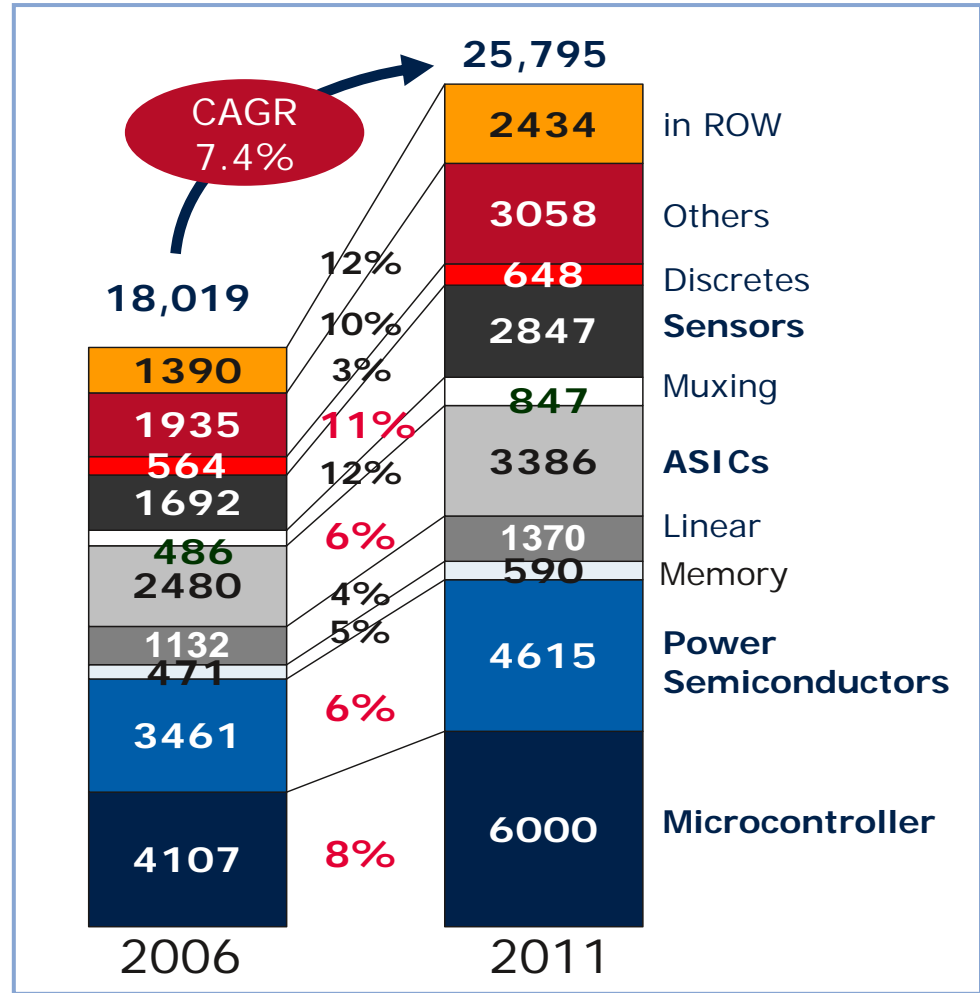
CAGR of 7.4% for the Automotive Semiconductor Market



Regional Automotive SC Market [USD m]



Automotive SC Product Market [USD m]



Source: Strategy Analytics, August 2006

April-2007

Copyright © Infineon Technologies 2007. All rights reserved.

Slide 23

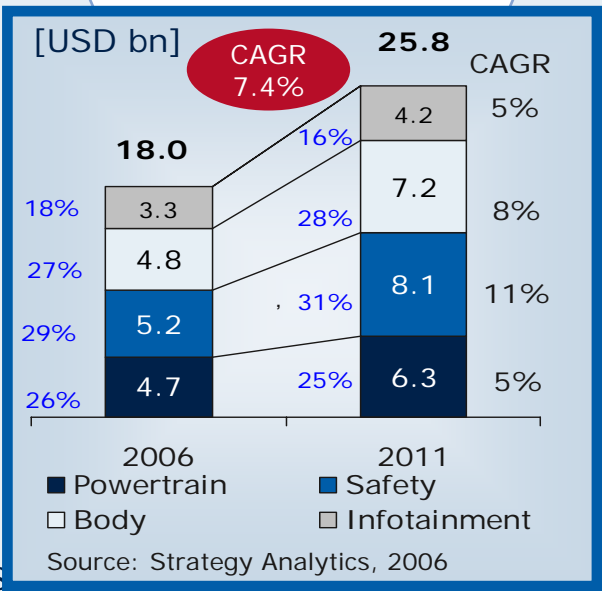
Areas of Growth in Automotive

Market

Applications

- Energy Efficiency**
 - Fuel consumption
 - Energy recovery
- Regulation**
 - Emission limits
 - Safety (TPMS, emergency call, VSC)
 - Toll collection
- Driving Experience**
 - Comfort features
 - Safety
 - Proactive warning, assistance and intervention
- Emerging Markets**
 - China and India

- Powertrain**
 - 32-bit motor control
 - Hybrid drivetrain
- Safety**
 - Airbag, ABS & VSC
 - Driver assistance systems
- Body**
 - Electrical motor control
 - LEDs for lighting
- Infotainment**
 - Integration of consumer devices into vehicle

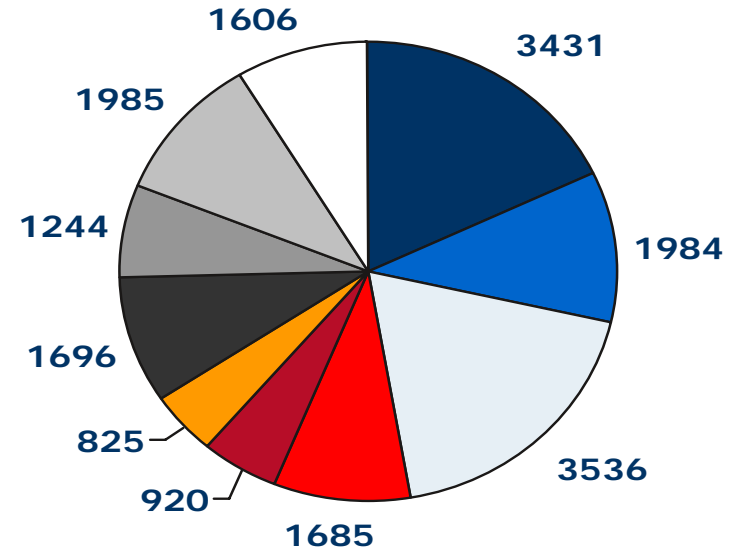
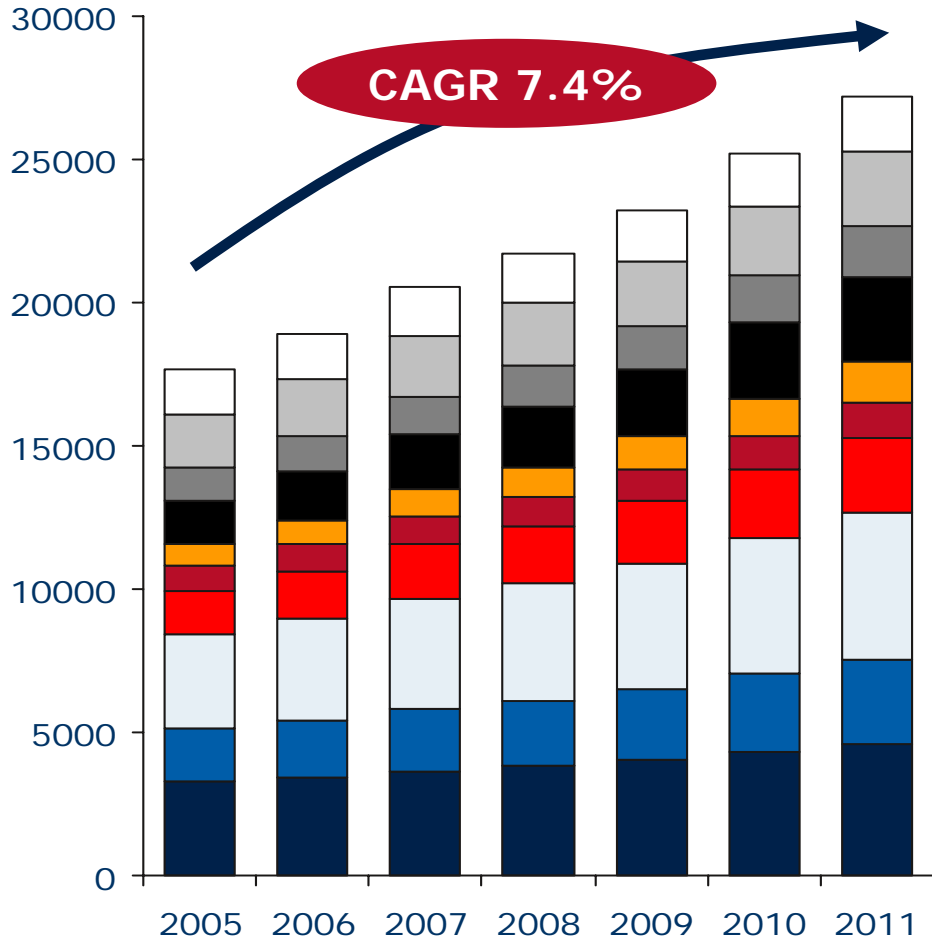


The Very Fragmented Industrial Market Represents 7.6% or USD 18.9 bn of the Total Semiconductor Market in 2006



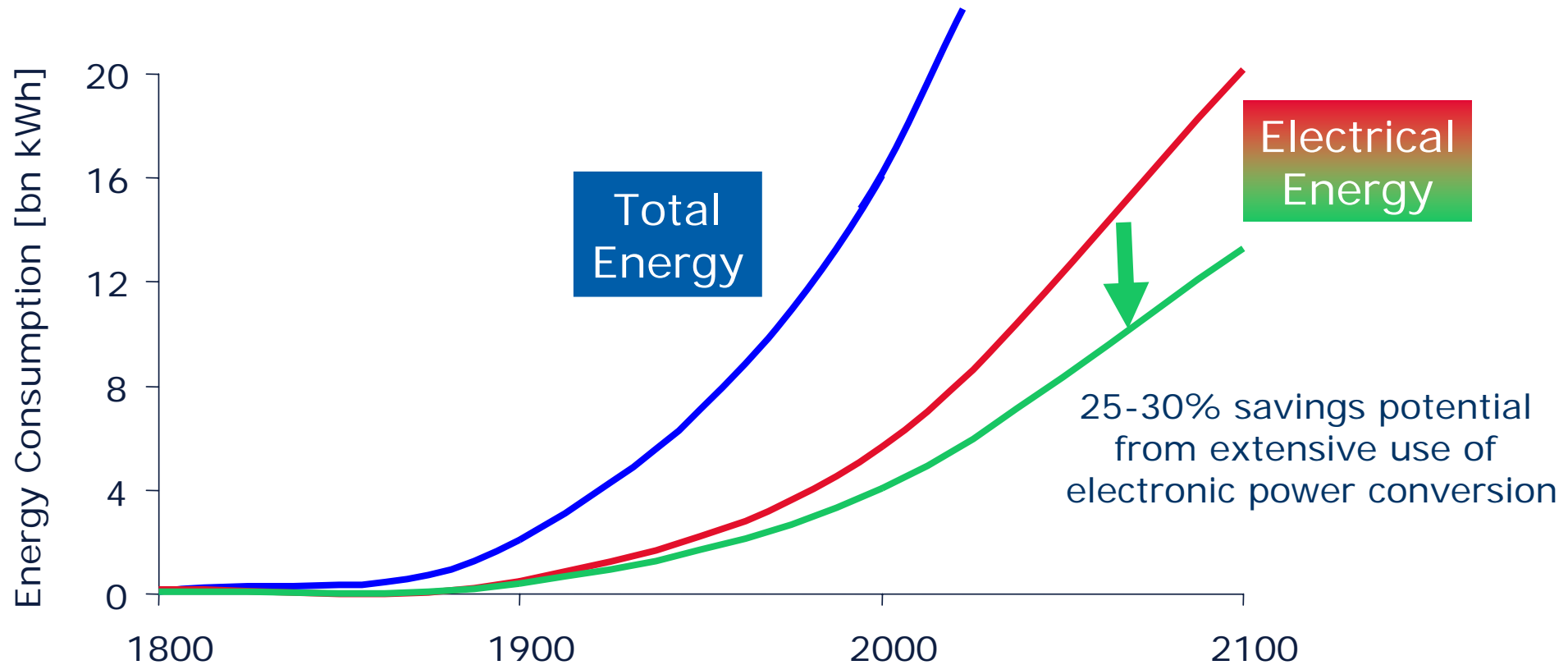
Industrial Semiconductor Market Revenues [USD m]

Industrial semiconductor market per Application [USD m]



Source: Semicast Estimates, October 2006

Energy Demand and Electricity Consumption are on the Rise – We Can Help to "Do More With Less"



Savings of 25% are possible in current electrical energy consumption which equals the demand of the USA.

Energy Generation and Distribution

Grid Coupling and Long Range Energy Transport



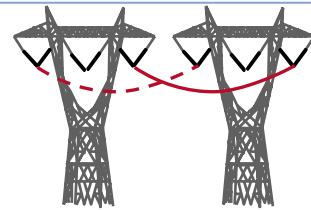
Energy Generation



- Hydro Power
- Wind power
- Solar power
- Fuel cells

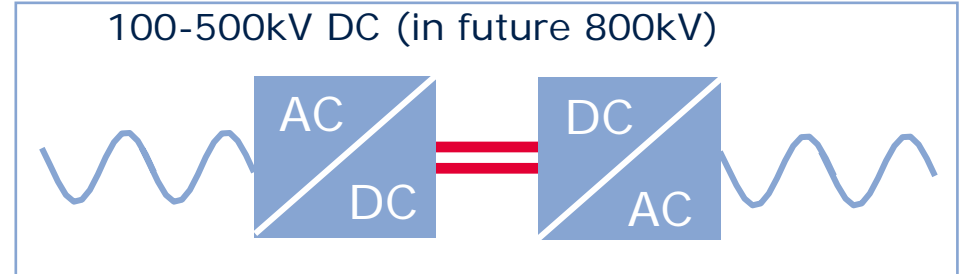
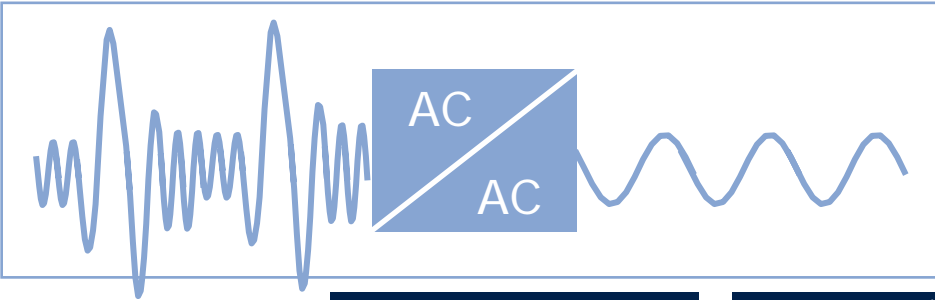
E.g. Wind Power : High efficiency coupling to grid

Energy Distribution



- FACTS and SVC
- HVDC Transmission

E.g. HVDC Transmission : Grid coupling, low loss energy transport



100-500kV DC (in future 800kV)

Power Discretes Bipolar Products

Power / IGBT Modules

Power ICs

Micro- controllers

IFX products
for energy
generation
and
distribution

- Thyristor and Diodes
- PressPACK
- CoolMOS
- IGBT

- EasyPIM
- EasyPACK
- EconoPACK
- IHM modules
- BIP modules
- Stacks
- PrimePACK

- EiceDRIVER

- 8-bit μ Cs
- 16-bit μ Cs
- 32-bit TriCore (μ C + DSP)

FACTS = Flexible Alternating Current Transmission Systems; SVC = Static Variable Compensator; HVDC = High Voltage Direct Current

Energy Consumption

Focus is on Efficient Power Conversion



Drives Applications Frequency Conversion

- Traction (trains)
- Speed controlled motors in
 - industrial
 - home
 - Pumps
- Automotive (Hybrids)



AC/DC Power Supplies

- Computer & server
- Adapter
- Charger
- TV, DVD, etc.
- Lighting
- Game console

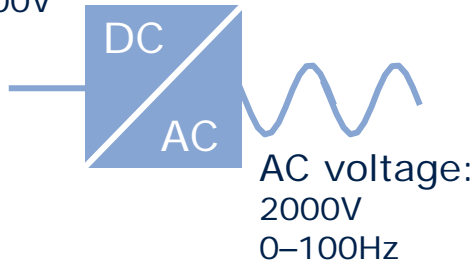


DC/DC Power Conversion

- Motherboard
- Graphics card
- Notebook
- Telecom
- VRMs
- Server

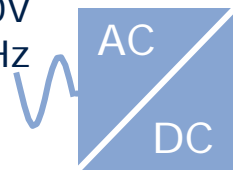


DC voltage:
300-3000V



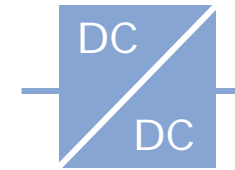
AC:

230V
50Hz



DC:

48V_{DC} Telecom
19V_{DC} Notebook
12V_{DC} Desktop
6V_{DC} Mobile charger



3.3V_{DC} Logic
2.5V_{DC} DSP
1.8V_{DC} Memory
1.2V_{DC} CPU

Power Discretes Bipolar Products

- CoolMOS
- thinQ! family (SiC Diode)
- Highspeed IGBTs
- OptiMOS

Power / IGBT Modules

- EasyPIM
- EasyPACK
- IsoPACK
- EconoPACK
- Thyristor / Diode modules

Power ICs

- PWM & PFC ICs
- CoolSET
- Integrated switches
- Gate drivers
- Smart ballast
- EiceDRIVER

Micro- controllers

- 8-bit μ Cs
- 16-bit μ Cs
- 32-bit TriCore (μ C + DSP)

IFX products
for energy
consumption

Today's Savings Potential from Using Electronic Power Conversion and Control



Stand-by power (TV)



~ **90%** savings potential

Power supply in a server



~ **12%** savings potential

Lighting



~ **25%** savings potential
(electronic ballast)

Motor control



30-40% savings potential
(rpm control)

Traction drives



20-30% savings potential
(energy recuperation)

Climate control



30-40% savings potential
(improved control)

Infineon –
Never stop thinking



Never stop thinking